

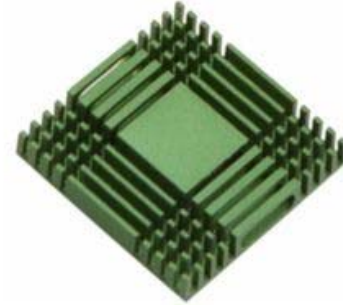


BOARD LEVEL COOLING - 3733

3733 is a series of square pin fin board level heat sinks designed to cool BGA and FPGA devices. Representative image only.

ORDERING INFORMATION

Part Number	Device Type
373324M00000G	BGA, FPGA
373324M00032G	BGA, FPGA



HEAT SINK DETAILS

Property	Details
Material	Aluminum
Finish	Green Anodize
Device Attachment Options	Tape
Thermal Interface Material 373324M00000G	N/A
Thermal Interface Material 373324M00032G	T405R Chomerics Tape for Metal Surfaces

Property	Details
Heat Sink Width (mm)	37.39
Heat Sink Length (mm)	37.39
Heat Sink Height (mm)	6.00
Heat Sink Mounting Direction	Horizontal, Vertical

MECHANICAL & PERFORMANCE

Drawing dimensions are shown in mm, (in)

